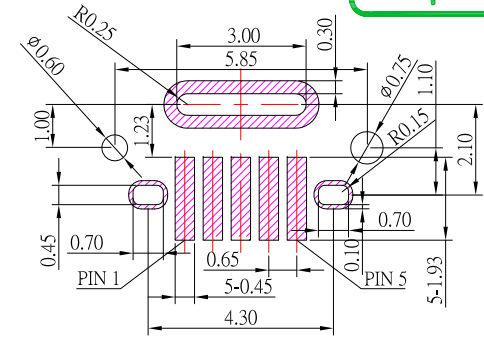
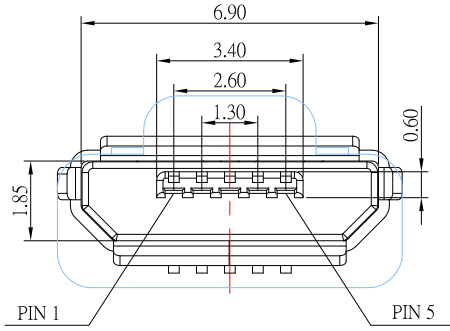




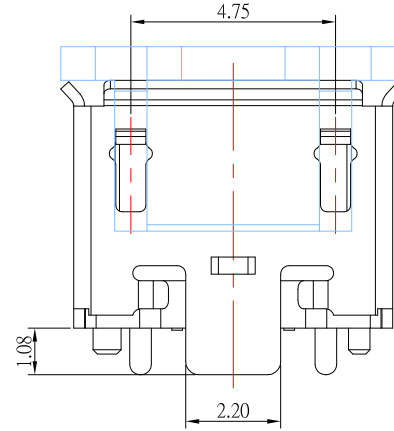
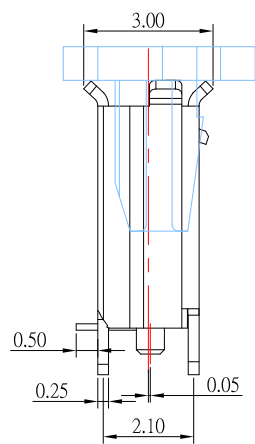
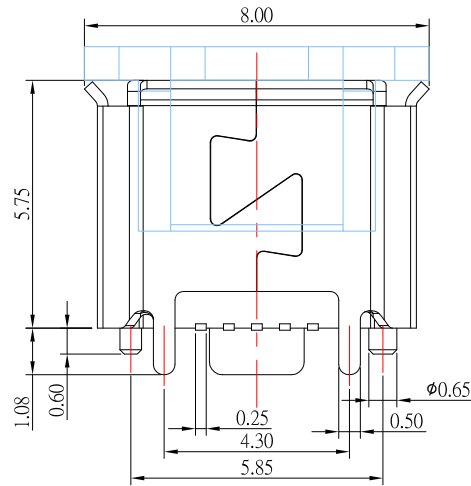
MRUSB-5B-VSE2-x-S165

鍍層厚度:

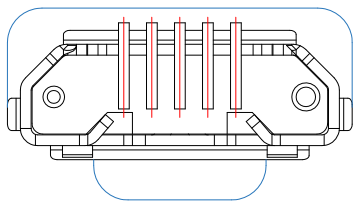
Blank : 1u"
2 : 15u"
3 : 30u"



P.C.B LAYOUT MOUNTING PATTERN



PIN NO.	SIGNAL NAME
PIN 1	VBUS
PIN 2	D-
PIN 3	D+
PIN 4	ID
PIN 5	GND



NOTES:

1.MATERIAL:

- 1.1 HOUSING: LCP, BLACK
- 1.2 CONTACT: PHOSPHOR BRONZE
- 1.3 SHELL: SUS

2.Finish:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;  
GOLD PLATED ON SOLDER BALLS ;  
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER

3.SPECIFICATION:

- 3.1 CURRENT RATING: 1.0 A
- 3.2 DIELECTRIC WITHSTANDING VOLTAGE: 100 VAC / MINUTE
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 100 MΩ MIN.
- 3.5 MATING FORCE: 3.57 Kgf MAX.
- 3.6 UNMATING FORCE: 1.0 Kgf MIN.
- 3.7 TEMPERATURE RANG : -30°C~80°C

6	新增PCB LAYOUT尺寸	Jack	031924
5	新增PIN標示和更新PCB LAYOUT位置	Jack	010924
4	新增尺寸	Jack	101823
3	更新圖面	Jack	092220
2	新增鍍層厚度選項	Jack	050420
1	新增PIN定義	Jack	021720
ITEM NO.	DESCRIPTION	DRAWN	DATE

**CONTACT** 建倚科技股份有限公司  
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :

Up to 5	±0.2
Above 5 ~ 15	±0.3
Above 15 ~ 30	±0.4
Above 30 ~ 50	±0.5
Angle	±0.3°

3RD. ANGEL'S



UNITS MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	03/19/24			
CHECKED BY:	DATE	FINISH	MODLE	MICRO USB 直立式 SMT TYPE 有捲邊
Jacky Chen	03/19/24			
APPROVED BY:	DATE	SCALE	DWG NO.	MRUSB-5B-VSE2-x-S165
Tony Kao	03/19/24	1 : 1		
		SHEET NO.	PART NO.	MRUSB-5B-VSE2-x-S165
		1 of 1		
				SIZE A4
				VER R6